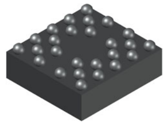
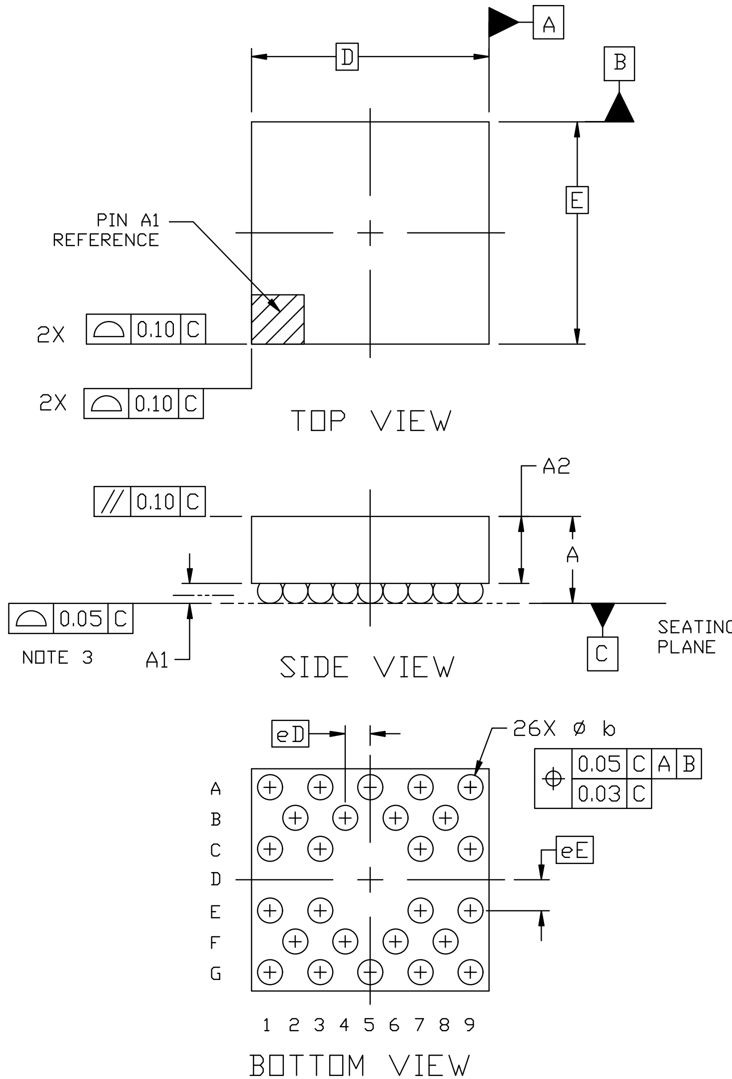


WLCSP26, 2.388x2.233
CASE 567CY
ISSUE B

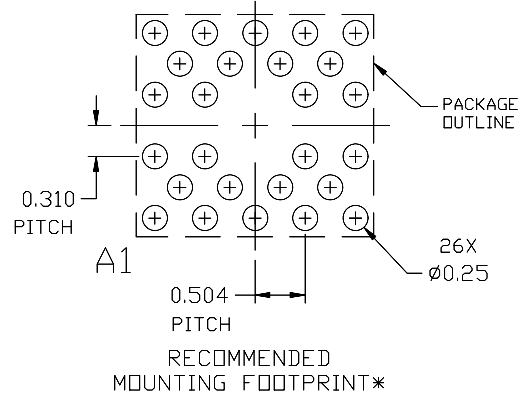
DATE 29 NOV 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

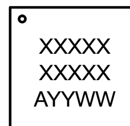
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.824	.874	0.924
A1	0.174	0.199	0.224
A2	0.650	0.675	0.700
b	0.24	0.265	0.29
D	2.388 BSC		
E	2.233 BSC		
eD	0.252 BSC		
eE	0.310 BSC		



RECOMMENDED
MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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